



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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P/N 97-AQ132D 132-Pin Amp Footprint PQFP-to-PGA Socket

FEATURES

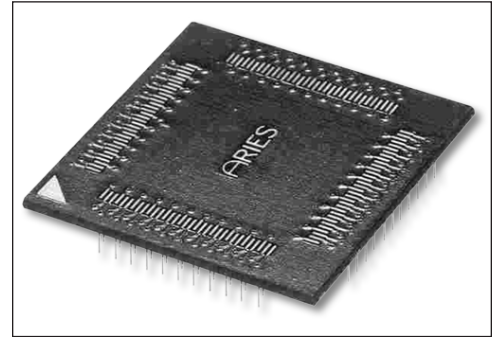
- Convert surface-mount PQFP packages to an Amp interstitial PGA footprint.
- Reduce costs by using less-expensive PQFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.
- RoHS version available, see Ordering Information

GENERAL SPECIFICATIONS

- BODY MATERIAL: Tg170 FR-4, 0.062 [1.58] thick, with 1-oz. Cu traces
- PADS: bare Cu protected with ENIG (Immersion Au over Electroless Ni) to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: Sn/Pb 93/7 per ASTM B579-73 over 100μ [2.54μ] Ni per SAE AMS-QQ-N-290 –or –
10μ [0.254μ] Au per MIL-G-45204 over 100μ [2.54μ] Ni per SAE AMS-QQ-N-290 for RC version
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- Will plug into existing PGA footprint with matching Pad assignments



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

Specify...

P/N 97-AQ132D or

P/N 97-AQ132D-P for Panelized form

P/N 97-AQ132D-RC or

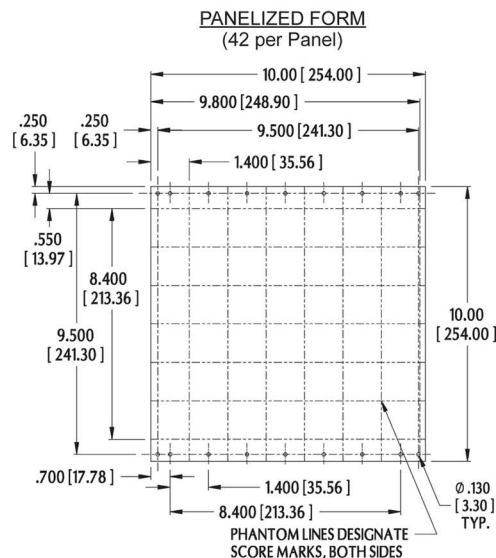
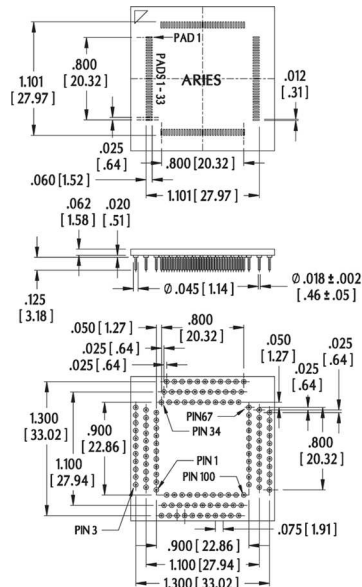
P/N 97-AQ132D-P-RC, for RoHS Panelized form

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW AND PIN-TO-PIN ±0.003 [±0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



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